

**SMAG Plastic-Encapsulate Diodes****RS1A THRU RS1M Fast Recovery Rectifier Diodes****Features**

- $I_{F(AV)}$ 1A
- V_{RRM} 50V-1000V
- High surge current capability
- Polarity: Color band denotes cathode

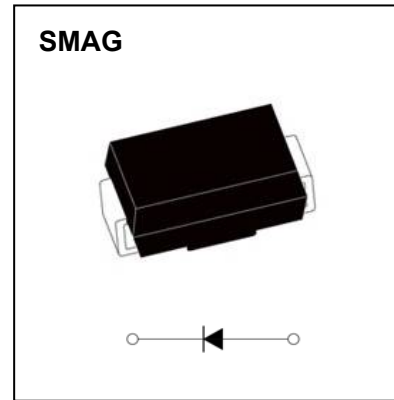
Applications

- Rectifier

Marking

- RS1X

X : From A To M

**Limiting Values(Absolute Maximum Rating)**

Item	Symbol	Unit	Test Conditions	RS1						
				A	B	D	G	J	K	M
Repetitive Peak Reverse Voltage	V _{RRM}	V		50	100	200	400	600	800	1000
Maximum RMS Voltage	V _{RMS}	V		35	70	140	280	420	560	700
Average Forward Current	I _{F(AV)}	A	60Hz Half-sine wave , Resistance load	1.0						
Surge(Non-repetitive)Forward Current	I _{FSM}	A	60Hz Half-sine wave , 1 cycle, Ta=25 ℃	30						
Operation Junction and Storage Temperature Range	T _J ,T _{STG}	℃		-55 ~ +150						

Electrical Characteristics (T=25°C Unless otherwise specified)

Item	Symbol	Unit	Test Condition		RS1						
					A	B	D	G	J	K	M
Peak Forward Voltage	V _F	V	I _F =1.0A		1.3						
Maximum reverse recovery time	t _{rr}	ns	I _F =0.5A,I _R =1.0A,I _{rr} =0.25A		150				250	500	
Peak Reverse Current	I _{RRM1}	μA	V _{RM} =V _{RRM}	T _a =25°C	5						
	T _a =125°C			50							
Thermal Resistance(Typical)	R _{θJ-A}	°C/W	Between junction and ambient		75						
	R _{θJ-L}		Between junction and terminal		27						
Juction Capacitance (Typical)	C _j	pF	Measured at 1MHZ and Applied Reverse Voltage of 4.0 V.D.C		6						

Notes:

Thermal resistance from junction to ambient and from junction to lead mounted on FR4 PCB double sided copper mini pad

Typical Characteristics

FIG.1: FORWARD CURRENT DERATING CURVE

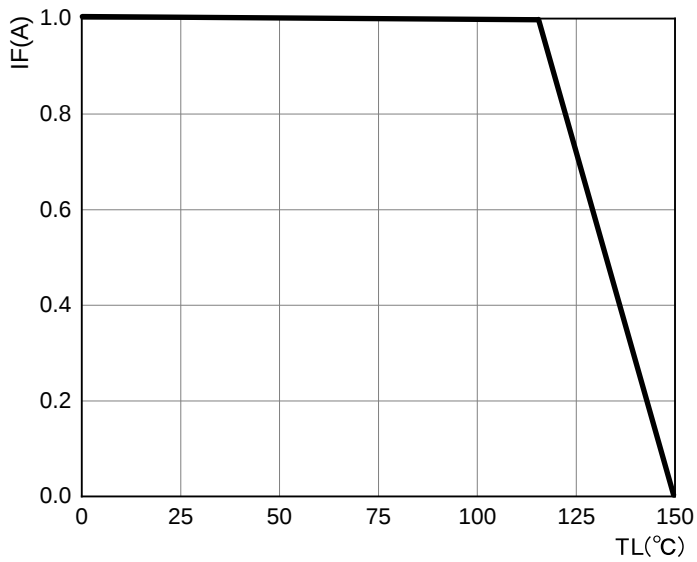


FIG 2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

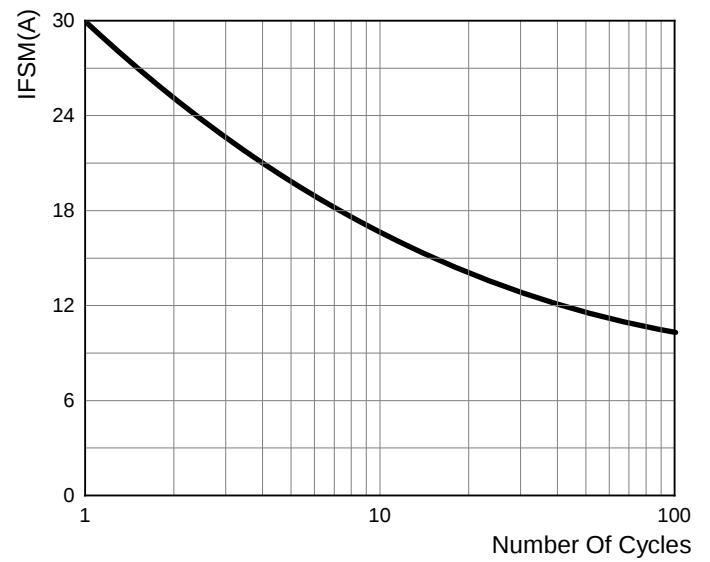


FIG.3 : TYPICAL FORWARD CHARACTERISTICS

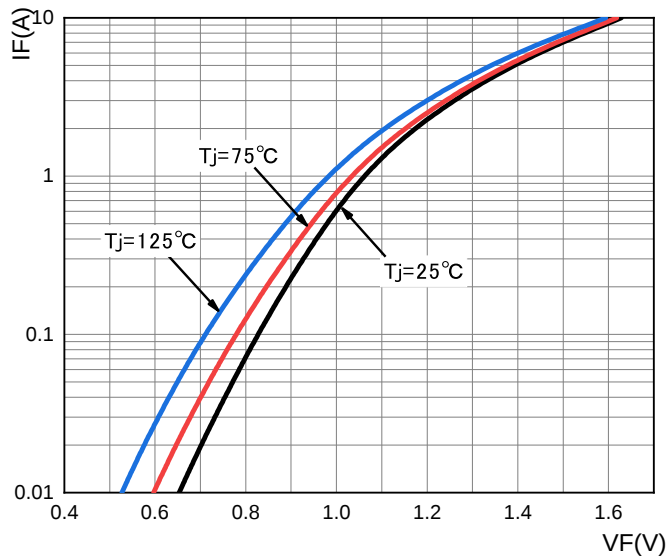
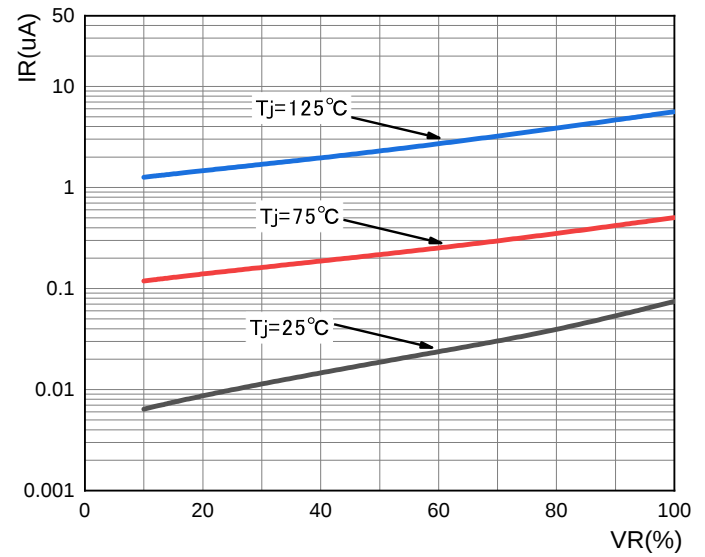
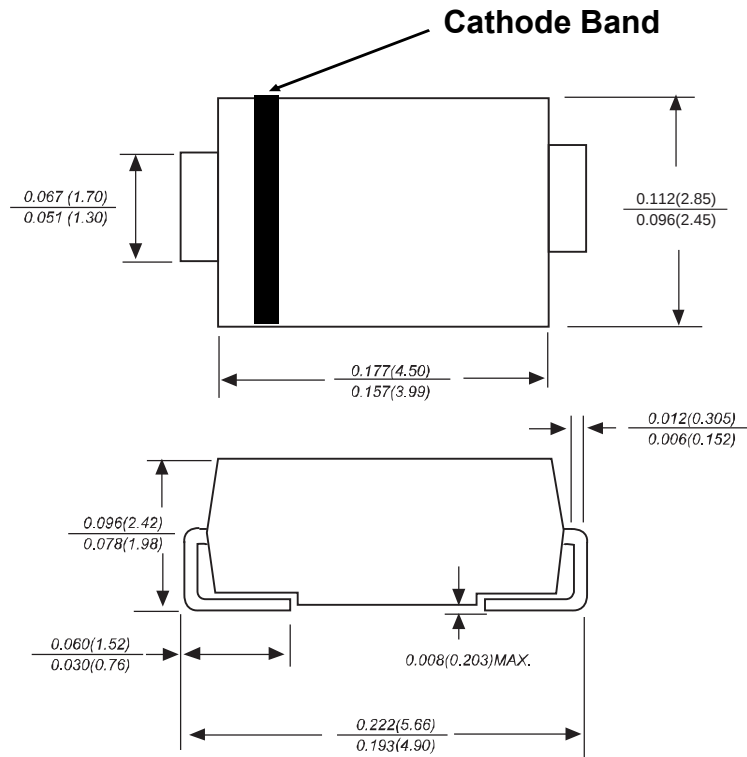


FIG.4 TYPICAL REVERSE CHARACTERISTICS

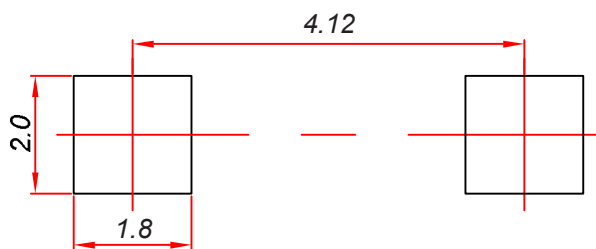


SMAG Package Outline Dimensions



Dimensions in inches and (millimeters)

SMAG Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05 \text{ mm}$.
3. The pad layout is for reference purposes only.

NOTICE

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Reel Taping Specifications For Surface Mount Devices- SMAG

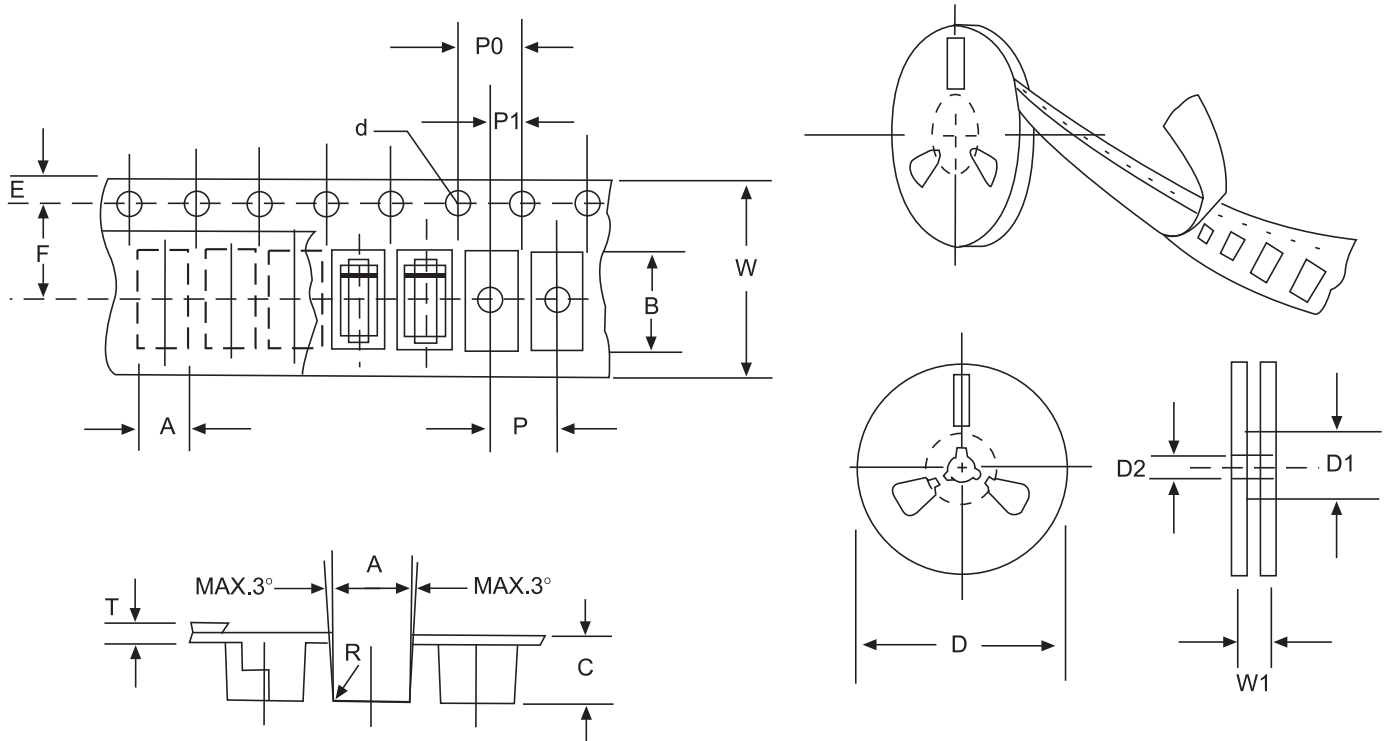


FIG:CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	SMAG mm(inch)
Carrier width	A	2.79±0.1(0.110±0.004)
Carrier length	B	5.33±0.1(0.210±0.004)
Carrier depth	C	2.36±0.1(0.093±0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11± 0.079)
Reel inner diameter	D1	75±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13±0.5(0.512±0.020)
Strocket hole position	E	1.75±0.1(0.069±0.004)
Punch hole position	F	5.5±0.05(0.217±0.002)
Punch hole pitch	P	4.0±0.1(0.157±0.004)
Sprocket hole pitch	P0	4.0±0.1(0.157±0.004)
Embossment center	P1	2.0±0.1(0.079±0.004)
Totall tape thickness	T	0.28±0.02(0.011±0.0008)
Tape width	W	12.0±0.2(0.472±0.008)
Reel width	W1	16.8±2.0(0.661±0.079)

NOTE:Devices are packed in accordance with EIA standard RS-481-A and specification given above.